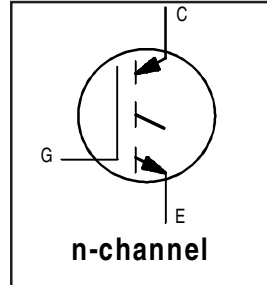


Features

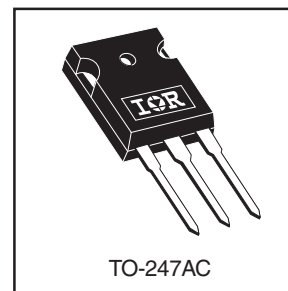
- UltraFast: Optimized for high operating frequencies up to 40 kHz in hard switching, >200 kHz in resonant mode
- New IGBT design provides tighter parameter distribution and higher efficiency than previous generations
- Optimized for power conversion; SMPS, UPS and welding
- Industry standard TO-247AC package



$V_{CES} = 1200V$
$V_{CE(on)} \text{ typ.} = 2.43V$
@ $V_{GE} = 15V, I_C = 21A$

Benefits

- Higher switching frequency capability than competitive IGBTs
- Highest efficiency available
- Much lower conduction losses than MOSFETs
- More efficient than short circuit rated IGBTs



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Breakdown Voltage	1200	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	41	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	21	
I_{CM}	Pulsed Collector Current ①	82	
I_{LM}	Clamped Inductive Load Current ②	82	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
E_{ARV}	Reverse Voltage Avalanche Energy ③	270	mJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	160	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	65	
T_J	Operating Junction and	-55 to + 150	$^\circ C$
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (0.063 in. (1.6mm) from case)	
	Mounting torque, 6-32 or M3 screw.	10 lbf•in (1.1N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.77	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	40	
Wt	Weight	6 (0.21)	—	g (oz)

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	18	—	—	V	$V_{GE} = 0V, I_C = 1.0A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.43	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	2.43	3.1	V	$I_C = 21A$ $V_{GE} = 15V$
		—	2.97	—		$I_C = 41A$ See Fig.2, 5
		—	2.47	—		$I_C = 21A, T_J = 150^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ⑤	16	24	—	S	$V_{CE} = 100V, I_C = 21A$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{GE} = 0V, V_{CE} = 1200V$
		—	—	2.0		$V_{GE} = 0V, V_{CE} = 10V, T_J = 25^\circ\text{C}$
		—	—	5000		$V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	86	130	nC	$I_C = 21A$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	13	20		$V_{CC} = 400V$ See Fig. 8
Q_{gc}	Gate - Collector Charge (turn-on)	—	29	44		$V_{GE} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	24	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 21A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail" See Fig. 9, 10, 14
t_r	Rise Time	—	24	—		
$t_{d(off)}$	Turn-Off Delay Time	—	220	330		
t_f	Fall Time	—	180	270	mJ	$T_J = 150^\circ\text{C}$, $I_C = 21A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail" See Fig. 11, 14
E_{on}	Turn-On Switching Loss	—	1.04	—		
E_{off}	Turn-Off Switching Loss	—	3.40	—		
E_{ts}	Total Switching Loss	—	4.44	5.2	ns	$T_J = 150^\circ\text{C}$, $I_C = 21A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail" See Fig. 11, 14
$t_{d(on)}$	Turn-On Delay Time	—	24	—		
t_r	Rise Time	—	25	—		
$t_{d(off)}$	Turn-Off Delay Time	—	310	—	mJ	$T_J = 150^\circ\text{C}$, $I_C = 21A, V_{CC} = 960V$ $V_{GE} = 15V, R_G = 10\Omega$ Energy losses include "tail" See Fig. 11, 14
t_f	Fall Time	—	380	—		
E_{ts}	Total Switching Loss	—	7.39	—		
L_E	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	1800	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ See Fig. 7 $f = 1.0MHz$
C_{oes}	Output Capacitance	—	120	—		
C_{res}	Reverse Transfer Capacitance	—	18	—		

Notes:

- ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature. (See fig. 13b)
- ② $V_{CC} = 80\%(V_{CES})$, $V_{GE} = 20V$, $L = 10\mu H$, $R_G = 10\Omega$, (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.

- ④ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ⑤ Pulse width $5.0\mu s$, single shot.

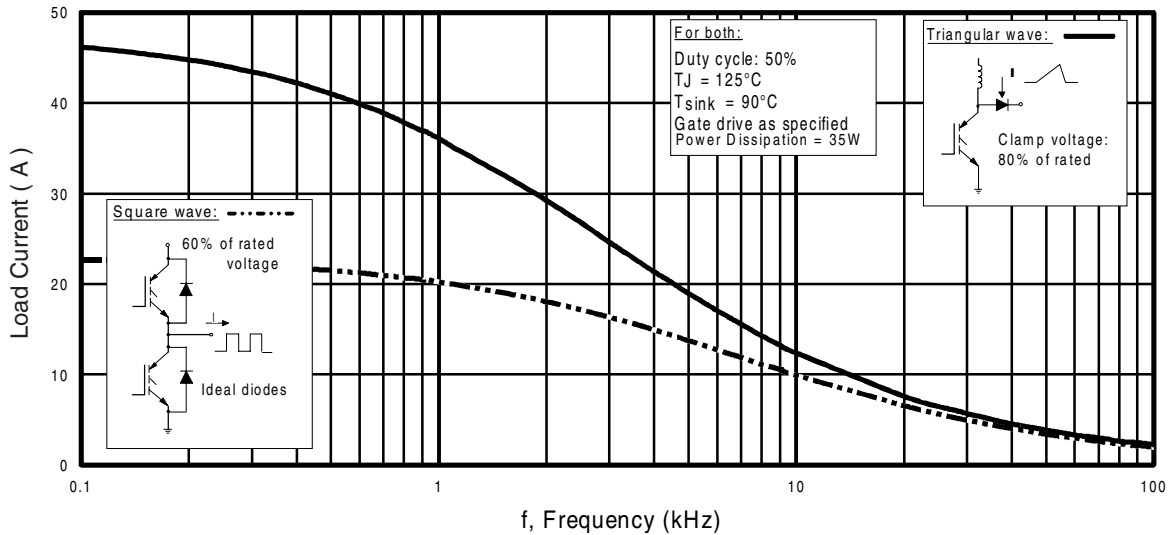


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

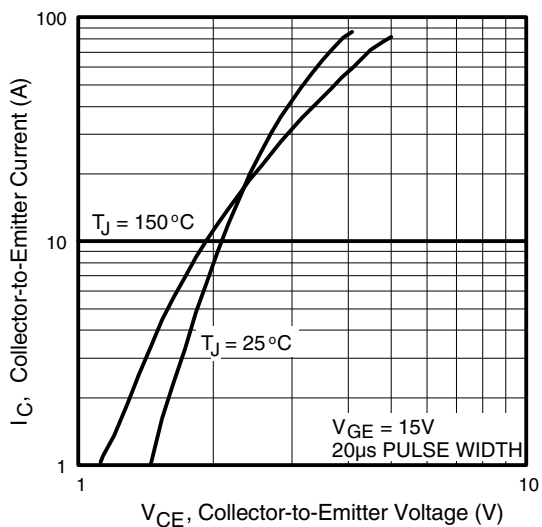


Fig. 2 - Typical Output Characteristics

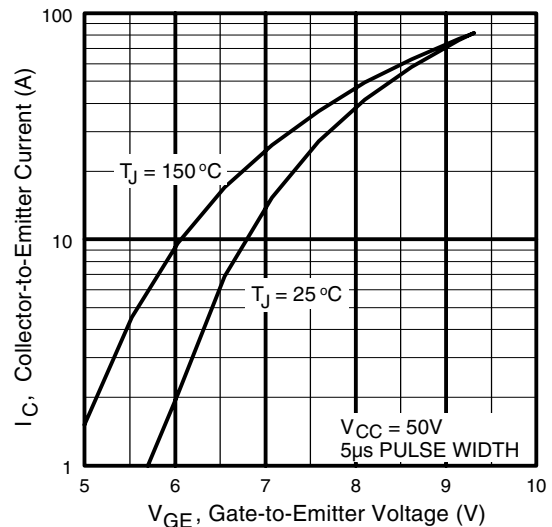


Fig. 3 - Typical Transfer Characteristics

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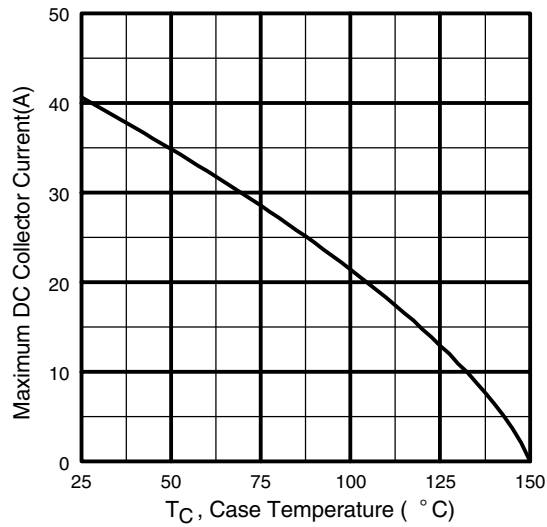


Fig. 4 - Maximum Collector Current vs. Case Temperature

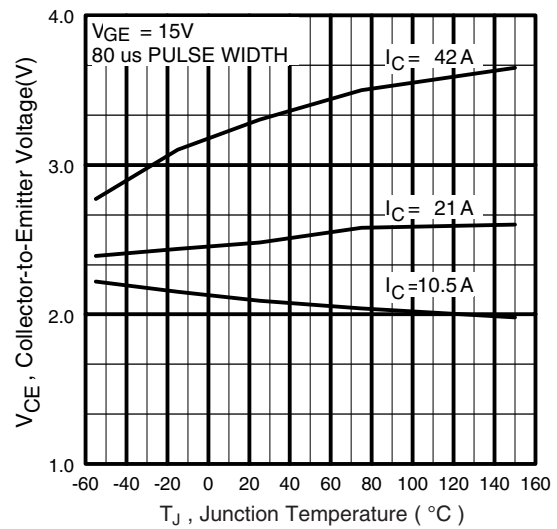


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

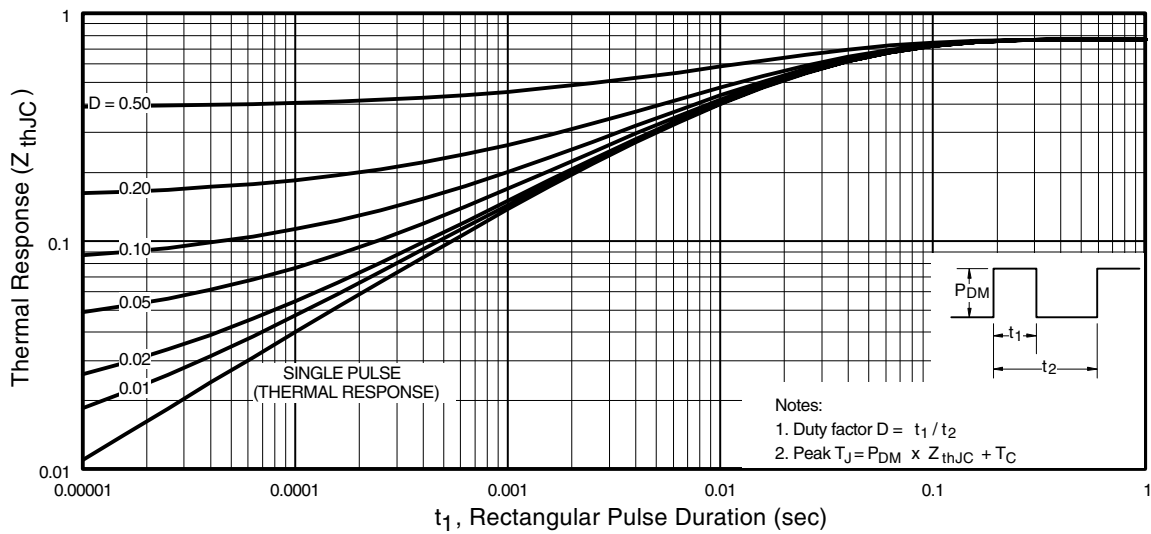


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

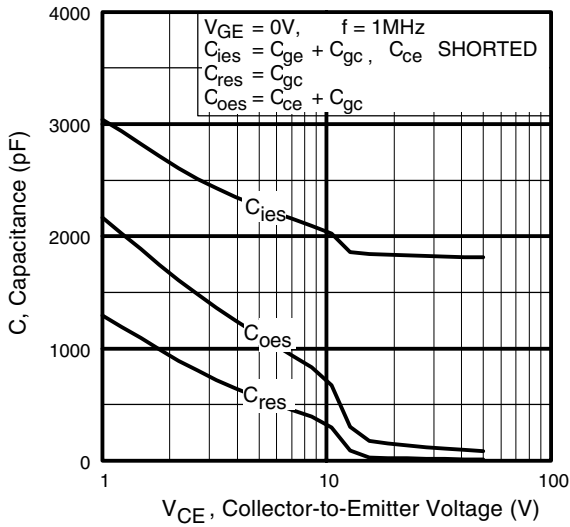


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

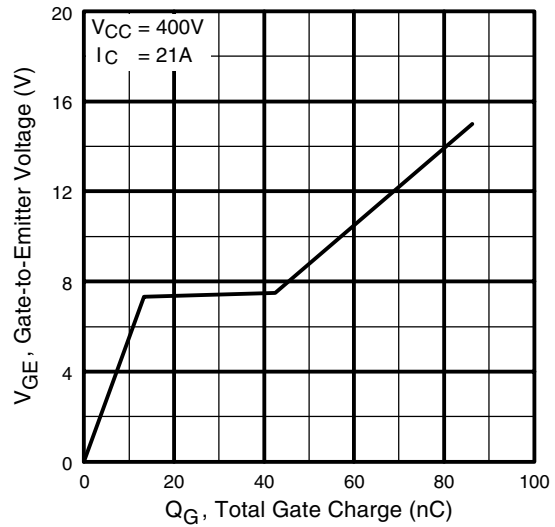


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

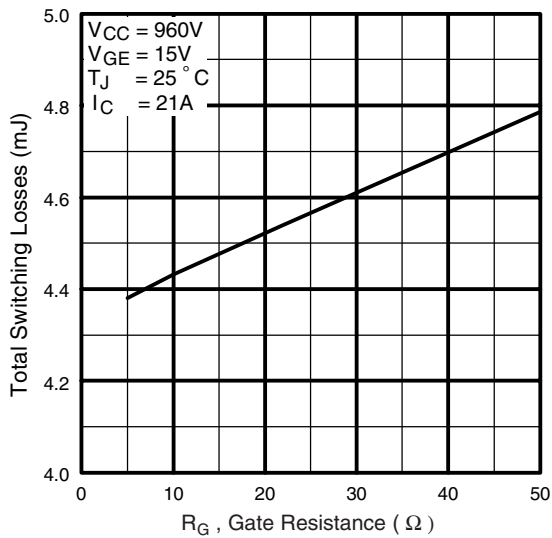


Fig. 9 - Typical Switching Losses vs. Gate Resistance

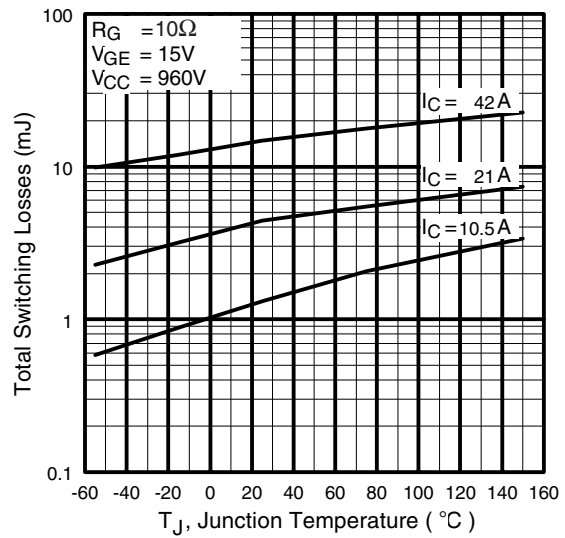


Fig. 10 - Typical Switching Losses vs. Junction Temperature

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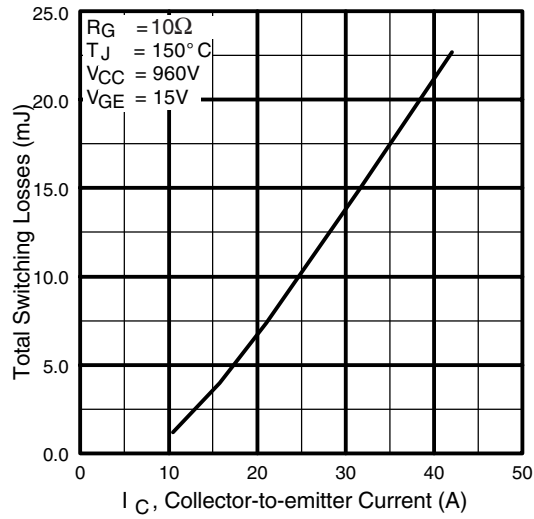


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

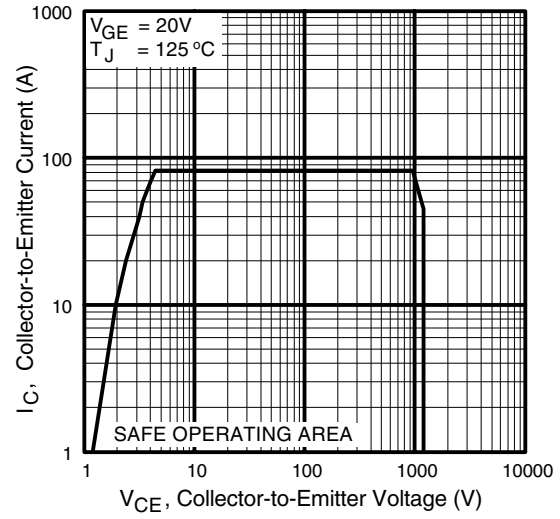


Fig. 12 - Turn-Off SOA

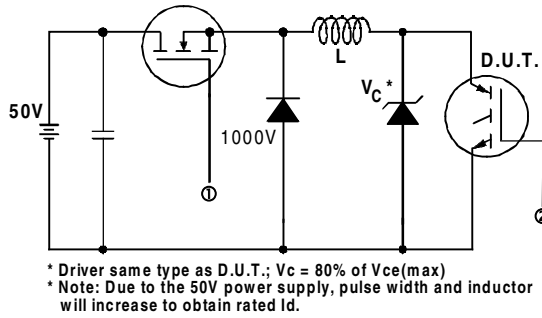


Fig. 13a - Clamped Inductive Load Test Circuit

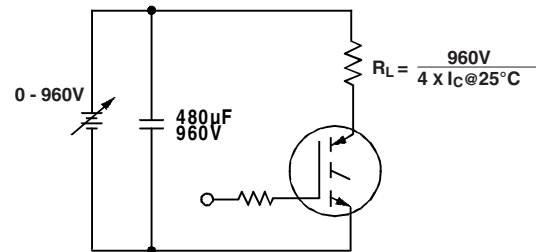


Fig. 13b - Pulsed Collector Current Test Circuit

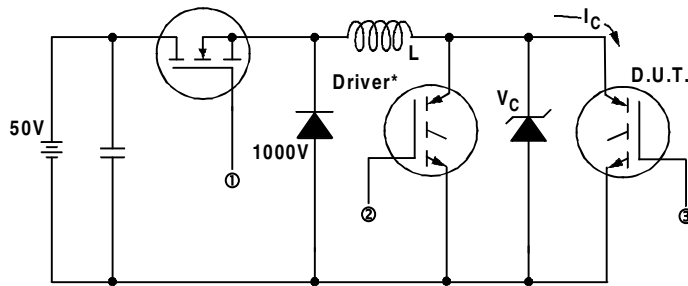


Fig. 14a - Switching Loss Test Circuit

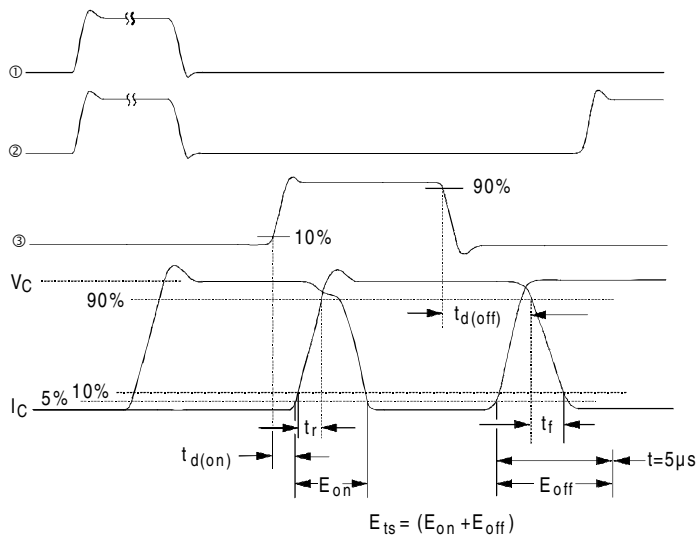


Fig. 14b - Switching Loss Waveforms

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Technical drawing of a mechanical part showing three views: front, top, and side. The drawing includes dimensions in millimeters (mm) and inches (in).

Front View Dimensions:

- Overall width: 15.90 (.626)
- Overall height: 20.30 (.800)
- Top surface width: 15.30 (.602)
- Top surface height: 19.70 (.775)
- Central hole diameter: $\varnothing 3.65$ (.143)
- Central hole position: 3.55 (.140)
- Top surface hole diameter: $\varnothing 0.25$ (.010) (M) D B (M)
- Top surface hole position: 5.50 (.217)
- Side hole diameter: $2 \times \varnothing 5.50$ (.217)
- Side hole position: 4.50 (.177)
- Bottom surface hole diameter: $3 \times \varnothing 1.40$ (.056)
- Bottom surface hole position: 1.00 (.039)
- Bottom surface hole diameter: $\varnothing 0.25$ (.010) (M) C A (S)
- Bottom surface hole position: 3.40 (.133)
- Bottom surface hole diameter: 3.00 (.118)
- Bottom surface hole diameter: 5.45 (.215)
- Bottom surface hole position: 2X

Top View Dimensions:

- Overall width: 15.90 (.626)
- Overall height: 20.30 (.800)
- Top surface width: 15.30 (.602)
- Top surface height: 19.70 (.775)
- Central hole diameter: $\varnothing 3.65$ (.143)
- Central hole position: 3.55 (.140)
- Top surface hole diameter: $\varnothing 0.25$ (.010) (M) D B (M)
- Top surface hole position: 5.50 (.217)
- Side hole diameter: $2 \times \varnothing 5.50$ (.217)
- Side hole position: 4.50 (.177)
- Bottom surface hole diameter: $3 \times \varnothing 1.40$ (.056)
- Bottom surface hole position: 1.00 (.039)
- Bottom surface hole diameter: $\varnothing 0.25$ (.010) (M) C A (S)
- Bottom surface hole position: 3.40 (.133)
- Bottom surface hole diameter: 3.00 (.118)
- Bottom surface hole diameter: 5.45 (.215)
- Bottom surface hole position: 2X

Side View Dimensions:

- Overall width: 5.30 (.209)
- Overall height: 4.70 (.185)
- Top surface width: 2.50 (.089)
- Top surface height: 1.50 (.059)
- Central hole diameter: $\varnothing 3.65$ (.143)
- Central hole position: 3.55 (.140)
- Top surface hole diameter: $\varnothing 0.25$ (.010) (M) D B (M)
- Top surface hole position: 5.50 (.217)
- Side hole diameter: $2 \times \varnothing 5.50$ (.217)
- Side hole position: 4.50 (.177)
- Bottom surface hole diameter: $3 \times \varnothing 1.40$ (.056)
- Bottom surface hole position: 1.00 (.039)
- Bottom surface hole diameter: $\varnothing 0.25$ (.010) (M) C A (S)
- Bottom surface hole position: 3.40 (.133)
- Bottom surface hole diameter: 3.00 (.118)
- Bottom surface hole diameter: 5.45 (.215)
- Bottom surface hole position: 2X

1 DIMENSIONS & TOLERANCING
PER ANSI Y14.5M, 1982.
2 CONTROLLING DIMENSION : INCH.
3 DIMENSIONS ARE SHOWN
MILLIMETERS (INCHES).
4 CONFORMS TO JEDEC OUTLINE
TO-247AC.

1 - GATE
2 - COLLECTOR
3 - EMITTER
4 - COLLECTOR

Dimensions in Millimeters and (Inches)

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Data and specifications subject to change without notice. 7/00